

PRODUCT NUMBER
59112-001

PRODUCT NUMBER DESCRIPTION: 59112 - X XX - XX - XXX XLF — LEAD FREE (∏) RETENTION (NOTES 6,10) PLATING -R: RETENTIVE LEG $S = 0.38 \mu m GOLD$ ON CONTACT AREA STACKER HEIGHT (NOTE 7) 0.38µm GOLD PACKAGING: - = BAGS ON TAIL (NOTE 5) U = TUBES G = 0.76µm GOLD P = TUBE WITH PICK-UP CAP ON CONTACT AREA A = TAPE & REEL WITH PICK-UP CAP 0.76µm GOLD POSITIONS PER ROW = "N" ON TAIL F = 0.20µm GOLD ON CONTACT AREA (02 to 25) OMIT FROM PRODUCT NUMBER FOR

LEAD FREE WITH RETENTIVE LEG PRODUCT

ON TAIL PIN STYLE OAL T = 0.76μm GOLD ON CONTACT AREA 08.2 2.54µm 100% MATTE TIN 09.6 10.2 28 11.8 13.5 14.1 34 15.6 36

NOTES:

0.20µm GOLD

I. MATERIAL HOUSING: HIGH TEMPERATURE THERMOPLASTIC UL 94V-0, COLOR BLACK

- 2. MATERIAL TERMINAL: COPPER ALLOY
- (3.) TO DETERMINE DIMENSIONS:

N = NUMBER OF POSITIONS PER ROW EX.: 10 POS., N x 2.00 = 20.00 TOTAL POSITIONS

- 4. 0.9kg MIN. PIN RETENTION IN EITHER DIRECTION.
- (5.) PACKAGING:

(A) STANDARD PACKAGING: IN POLY BAGS.

(B) SPECIAL PACKAGING: IN TUBE OR TAPE AND REEL.
FOR TUBE AN OPTIONAL PICK-UP CAP IS PROVIDED AT
THE CENTER OF THE PRODUCT FOR PICK AND PLACE APPLICATIONS.
PICK-UP CAP IS STANDARD IN TAPE AND REEL.

FOR ALL SPECIAL PACKAGING, FCI MUST BE CONTACTED FOR
AVAILABILITY IN SIZE REQUESTED.

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(6.) RETENTION LEG:

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2.3kg MAX INSERTION FORCE AND Ikg MIN RETENTION FORCE PER
RETENTIVE PIN USING 1.57 THICK CIRCUIT BOARD AND RECOMMENDED
RECOMMENDED HOLE PATTERN. RETENTIVE LOCATION AT THE
DISCRETION OF THE MANUFACTURER. RETENTION IS TWO PINS PER
PART ADJACENT TO ONE ANOTHER.

- STACK HEIGHT IS DETERMINED BY CUSTOMER APPLICATION REQUIREMENTS.

 SPECIFIED IN mm. EXAMPLE: 3.7mm STACK HEIGHT=59112-XXX-037X.
- 8 POST LENGTH IS DETERMINED BY: (OAL)-(2.50)-(STACK HGT.) = POST LENGTH. MINIMUM MATING LGTH. TO BE 2.0mm.
- DIM I.O APPLIES TO MOLDED SIDE(S) ONLY. IF SIDE(S) ARE BROKEN,
 DIM I.5 MAX APPLIES.
- (0) OMIT FROM PRODUCT NUMBER IF FEATURE IS NOT APPLICABLE.

(I). P/N:59112-XXXLF IS SAME AS P/N:59112-XXX. THE SUFFIX 'LF' IS ADDED FOR EASY LEAD FREE IDENTIFICATION.

12. THE HOUSING WILL WITHSTAND EXPOSURE TO 255°C PEAK TEMPERATURE FOR 10 SECONDS IN A CONVECTION, INFRA-RED OR VAPOR PHASE REFLOW OVEN.

13. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.57MM MINIMUM THICK CIRCUIT BOARD

14. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.

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2.00mm UNSHROUDED HEADER
BOARD TO BOARD THRU-HOLE

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Rev

REV F - 2006-04-17

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3PDM: Rev:J STATUSR